

L Number	Hits	Search Text	DB	Time stamp
2	73863	"heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 13:34
3	9409	"radial projections"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 13:34
4	35	"heat sink" and "radial projections"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 13:52
5	160	"cylindrical heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 13:52
6	92	"rectangular heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 13:52
7	8	"conical heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 13:55
8	11	"tapered heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 14:00
9	232	"heat sink" near3 "electrically insulated"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 14:13
10	140	"heat sink" near1 "electrically insulated"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 14:14
11	618	(237/12.3r).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 14:39
12	0	"shape of the heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 14:39
13	118	"heat sink shape"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/19 14:40
-	561	(219/209).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/17 16:06
-	80	transistor and ((219/209).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/13 16:43

	481	((219/209).CCLS.) not (transistor and ((219/209).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 16:52
	2	("6348672").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:05
	5	("3139515" "3801278" "4216371" "4336444" "5320030").PN.	USPAT	2004/09/13 16:53
	0	6348672.URPN.	USPAT	2004/09/13 16:56
	2311	"power transistor" and "heat sink"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:08
	325556	"circuit board"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/13 17:08
	2353	(165/80.3).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 09:06
	1966	(219/203,530,540).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 09:07
	1978	(219/202,530,540).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 09:07
	21	"power transistor" and ((219/202,530,540).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 09:07
	1	"power transistor" and ((237/12.3r).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 09:13
	101	((165/80.3).CCLS.) and "power transistor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 09:13
	1074	(361/719).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 09:46
	793	("power transistor" and "heat sink") and "circuit board"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 10:10
	40	((361/719).CCLS.) and ((power transistor" and "heat sink") and "circuit board")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 10:11

-	1034	((361/719).CCLS.) not (("power transistor" and "heat sink") and "circuit board")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 10:23
-	2	("20040129695").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 10:43
-	635	(((361/719).CCLS.) not (("power transistor" and "heat sink") and "circuit board")) and hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 10:43
-	10	("5473510" "5671121" "5825625" "5990550" "6181567" "6229216" "6286208" "6366467" "6392296" "6407924").PN.	USPAT	2004/09/14 11:01
-	2	("6494723").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:19
-	4	"2002011484"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:20
-	3	"2001050843"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:21
-	2	"20010050843"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:21
-	2	("6392207").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:25
-	3086	"heater block"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:25
-	26554	"power transistor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:25
-	23	"heater block" and "power transistor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 16:26